



IAS Conn



C1



C3



C2



J4



**ALIF**  
SEMICONDUCTOR

C5



C4

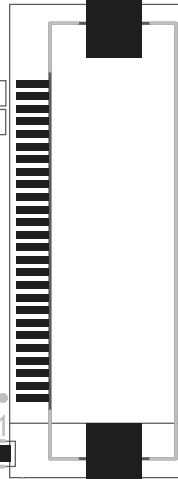
J1



R1



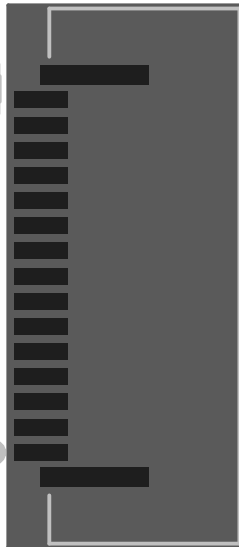
D1



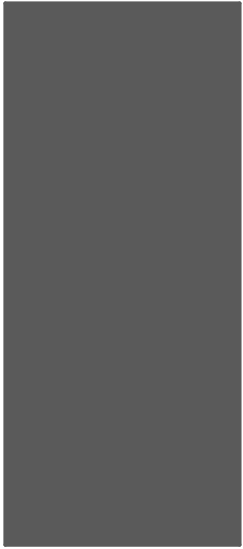
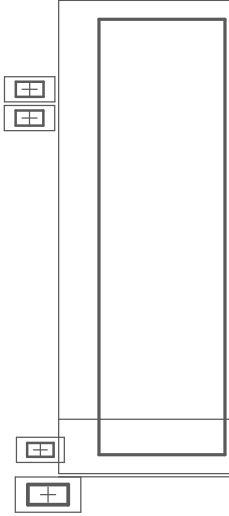
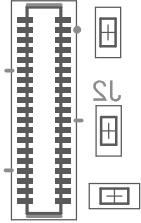
C6

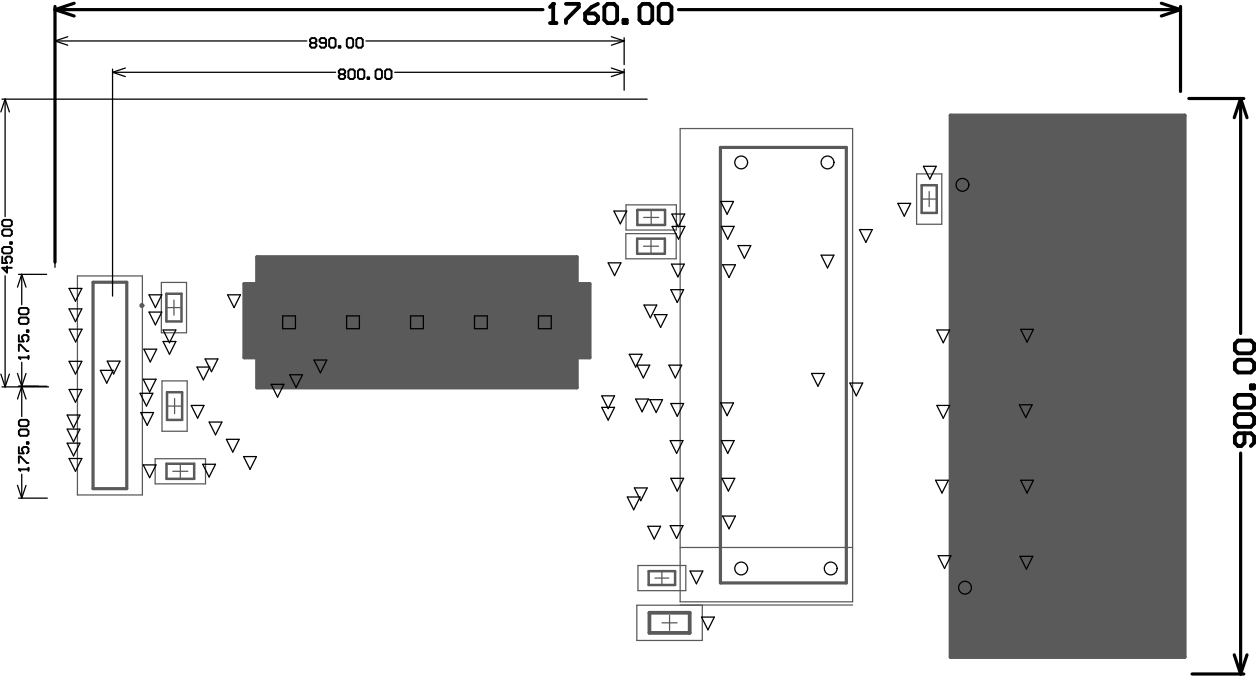


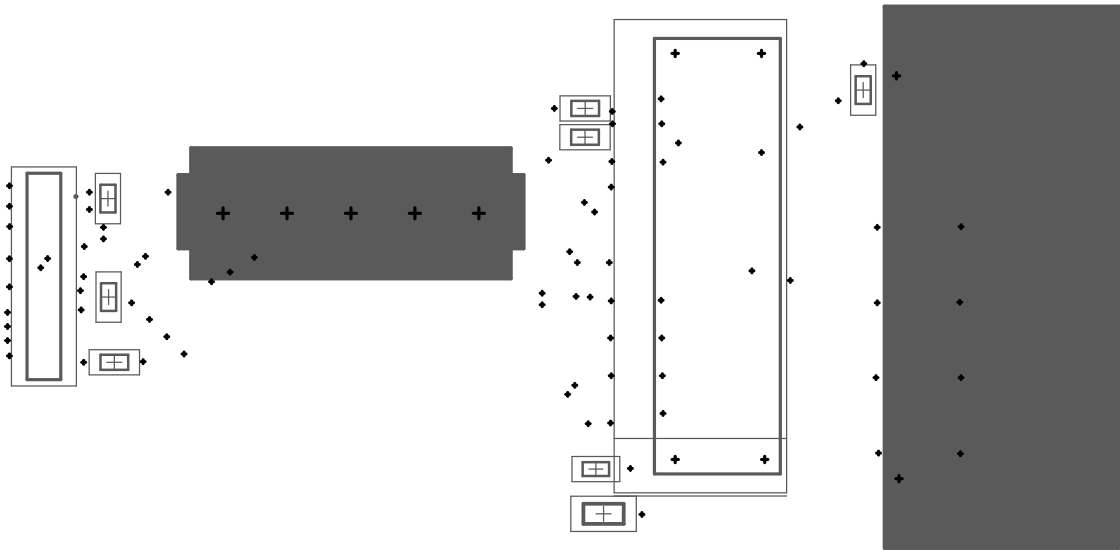
J3














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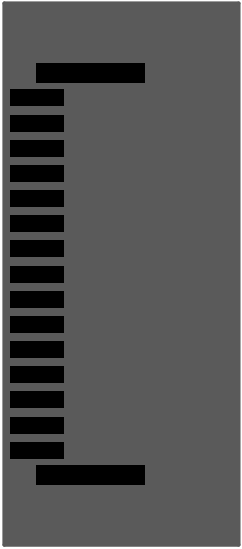
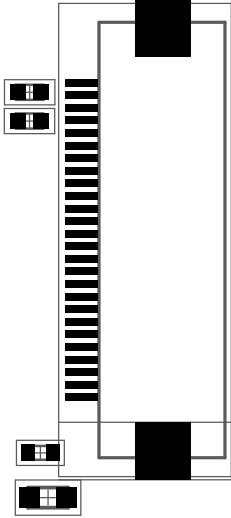
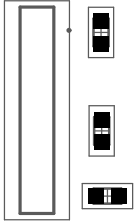




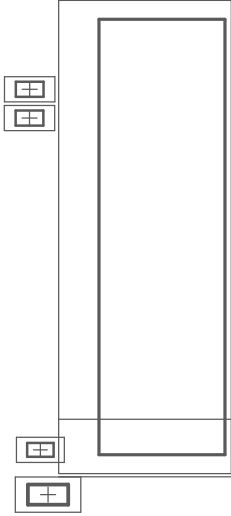
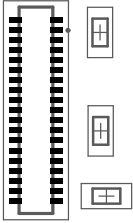


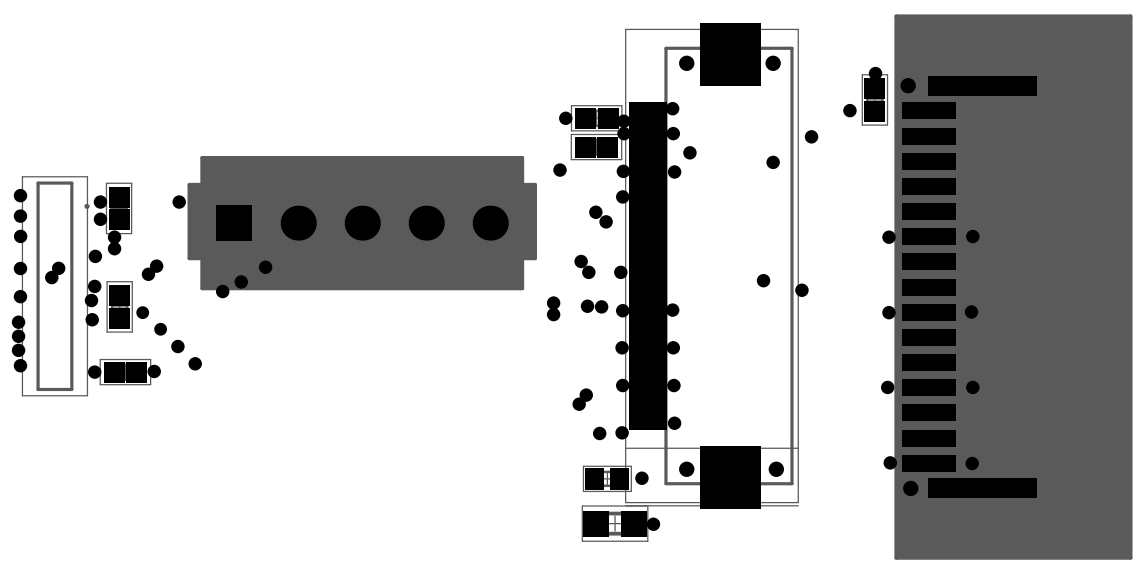
# Board Stack Report

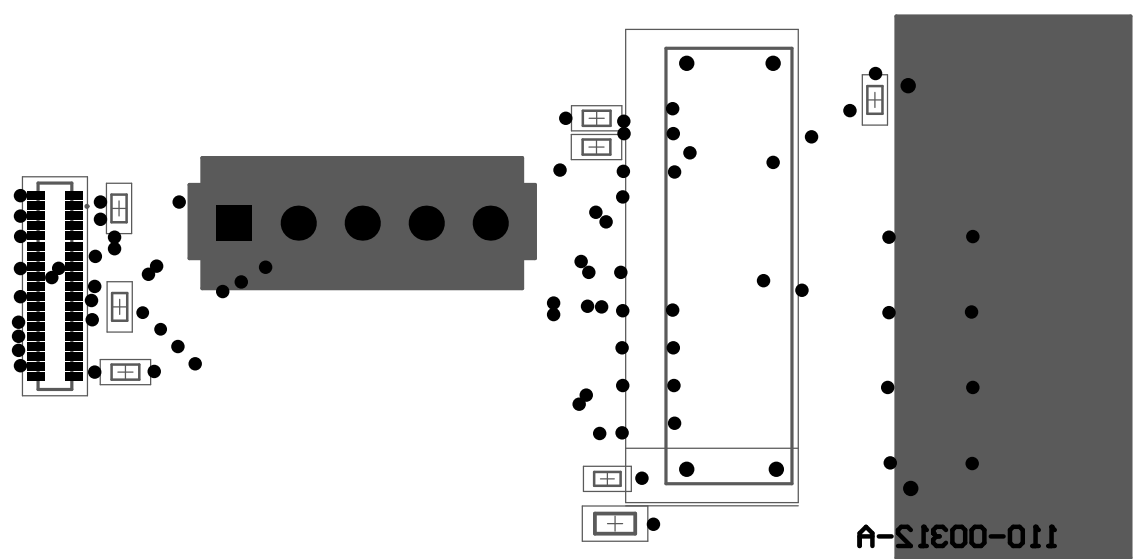
Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Overlay		0mil	
2		Top Solder	Solder Resist	0.4mil	3.5
3		Top Layer		1.4mil	
4		Dielectric 2	PP-006	4.2mil	4.1
5		L2(GND)	CF-004	0.689mil	
6		Dielectric 1	FR-4	28mil	4.7
7		L3(V_2V8)	CF-004	0.689mil	
8		Dielectric 3	PP-006	4.2mil	4.1
9		Bottom Layer		1.4mil	
10		Bottom Solder	Solder Resist	0.4mil	3.5
11		Bottom Overlay		0mil	
Height : 41.378mil					











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